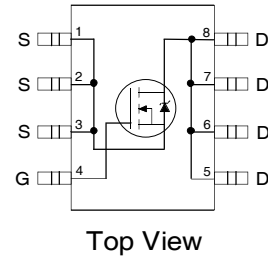


**Application**

- Generation VTechnology
- Ultra Low On-Resistance
- N-Channel Mosfet
- Surface Mount
- Available in Tape &Reel
- Dynamic dv/dt Rating
- Fast Switching
- 100% Rg Tested
- Lead-Free



Top View

**Features**

- $V_{DS} (V) = 30V$
- $R_{DS(ON)} < 12m\Omega$  ( $V_{GS} = 10V$ )
- $R_{DS(ON)} < 17m\Omega$  ( $V_{GS} = 4.5V$ )

**Absolute Maximum Ratings**

Symbol	Parameter	Max	Units
$V_{DS}$	Drain-to-Source Voltage	30	V
$V_{GS}$	Gate-to-Source Voltage	$\pm 20$	
$I_D @ T_A = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$	13	A
$I_D @ T_A = 70^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$	9.2	
$I_{DM}$	Pulsed Drain Current ①	58	
$P_D @ T_A = 25^\circ C$	Power Dissipation	2.5	W
	Linear Derating Factor	0.02	mW/°C
$E_{AS}$	Single Pulse Avalanche Energy ②	260	mJ
dv/dt	Peak Diode Recovery dv/dt ③	5.0	V/ns
$T_J, T_{STG}$	Junction and Storage Temperature Range	-55 to +150	°C

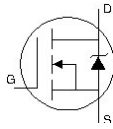
**Thermal Resistance Ratings**

Symbol	Parameter	Typ	Max	Units
$R_{\theta JL}$	Junction-to-Drain Lead	—	20	°C/W
$R_{\theta JA}$	Junction-to-Ambient ④	—	50	

**Electrical Characteristics @ T<sub>J</sub> = 25°C (unless otherwise specified)**

Symbol	Parameter	Min	Typ	Max	Units	Conditions
V <sub>(BR)DSS</sub>	Drain-to-Source Breakdown Voltage	30	—	—	V	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA
ΔV <sub>(BR)DSS</sub> /ΔT <sub>J</sub>	Breakdown Voltage Temp. Coefficient	—	0.034	—	V/°C	Reference to 25°C, I <sub>D</sub> = 1mA
R <sub>DS(on)</sub>	Static Drain-to-Source On-Resistance	—	—	12	mΩ	V <sub>GS</sub> = 10V, I <sub>D</sub> = 7.3A ④
		—	—	17		V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 3.7A ④
V <sub>GS(th)</sub>	Gate Threshold Voltage	1.0	—	3.0	V	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA
g <sub>fs</sub>	Forward Transconductance	10	—	—	S	V <sub>DS</sub> = 10V, I <sub>D</sub> = 3.7A
I <sub>DSS</sub>	Drain-to-Source Leakage Current	—	—	12	μA	V <sub>DS</sub> = 30V, V <sub>GS</sub> = 0V
		—	—	25		V <sub>DS</sub> = 24V, V <sub>GS</sub> = 0V, T <sub>J</sub> = 125°C
I <sub>GSS</sub>	Gate-to-Source Forward Leakage	—	—	-100	nA	V <sub>GS</sub> = -20V
	Gate-to-Source Reverse Leakage	—	—	100		V <sub>GS</sub> = 20V
Q <sub>g</sub>	Total Gate Charge	—	52	79	nC	I <sub>D</sub> = 7.3A
Q <sub>gs</sub>	Gate-to-Source Charge	—	6.1	9.2		V <sub>DS</sub> = 24V
Q <sub>gd</sub>	Gate-to-Drain ("Miller") Charge	—	16	23		V <sub>GS</sub> = 10V, See Fig. 6 and 9 ④
R <sub>G</sub>	Gate Resistance	—	—	3.7	Ω	
t <sub>d(on)</sub>	Turn-On Delay Time	—	8.6	—	ns	V <sub>DD</sub> = 15V
t <sub>r</sub>	Rise Time	—	50	—		I <sub>D</sub> = 7.3A
t <sub>d(off)</sub>	Turn-Off Delay Time	—	52	—		R <sub>G</sub> = 6.2 Ω
t <sub>f</sub>	Fall Time	—	46	—		R <sub>G</sub> = 2.0Ω, See Fig. 10 ④
C <sub>iss</sub>	Input Capacitance	—	1800	—	pF	V <sub>GS</sub> = 0V
C <sub>oss</sub>	Output Capacitance	—	680	—		V <sub>DS</sub> = 25V
C <sub>rss</sub>	Reverse Transfer Capacitance	—	240	—		f = 1.0MHz, See Fig. 5

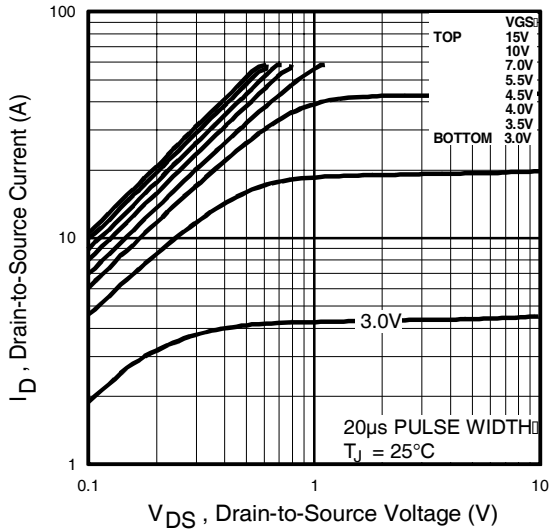
**Source-Drain Ratings and Characteristics**

Symbol	Parameter	Min.	Typ.	Max.	Units	Conditions
I <sub>S</sub>	Continuous Source Current (Body Diode)	—	—	3.1	A	MOSFET symbol showing the integral reverse p-n junction diode. 
I <sub>SM</sub>	Pulsed Source Current (Body Diode) ①	—	—	58		
V <sub>SD</sub>	Diode Forward Voltage	—	—	1.0	V	T <sub>J</sub> = 25°C, I <sub>S</sub> = 7.3A, V <sub>GS</sub> = 0V ③
t <sub>rr</sub>	Reverse Recovery Time	—	74	110	ns	T <sub>J</sub> = 25°C, I <sub>F</sub> = 7.3A
Q <sub>rr</sub>	Reverse Recovery Charge	—	200	300	nC	di/dt = 100A/μs ③

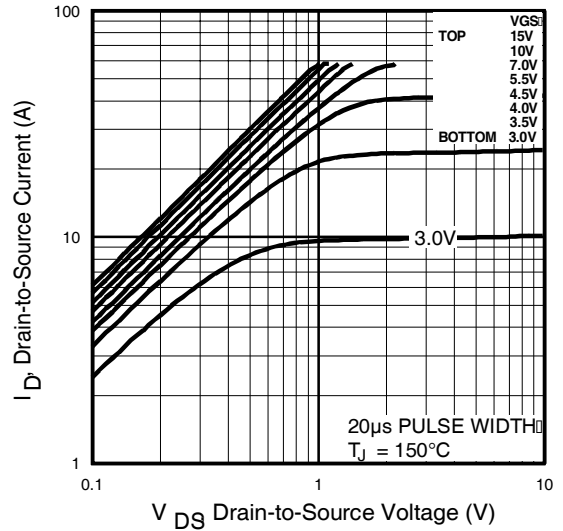
**Notes:**

- ① Repetitive rating; pulse width limited by max. junction temperature. ( See fig. 11 )
- ② Starting T<sub>J</sub> = 25°C, L = 9.8mH  
R<sub>G</sub> = 25Ω, I<sub>AS</sub> = 7.3A. (See Figure 12)
- ③ I<sub>SD</sub> ≤ 7.3A, di/dt ≤ 100A/μs, V<sub>DD</sub> ≤ V<sub>(BR)DSS</sub>,  
T<sub>J</sub> ≤ 150°C
- ④ Pulse width ≤ 300μs; duty cycle ≤ 2%.
- ⑤ Surface mounted on FR-4 board
- ⑥ R<sub>θ</sub> is measured at T<sub>J</sub> approximately 90°C

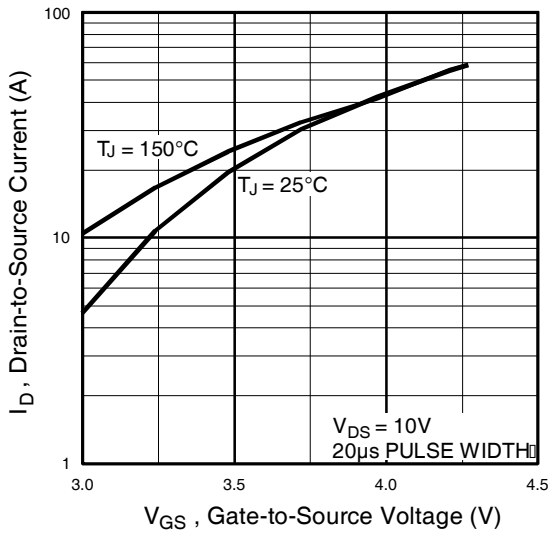
**Typical Characteristics**



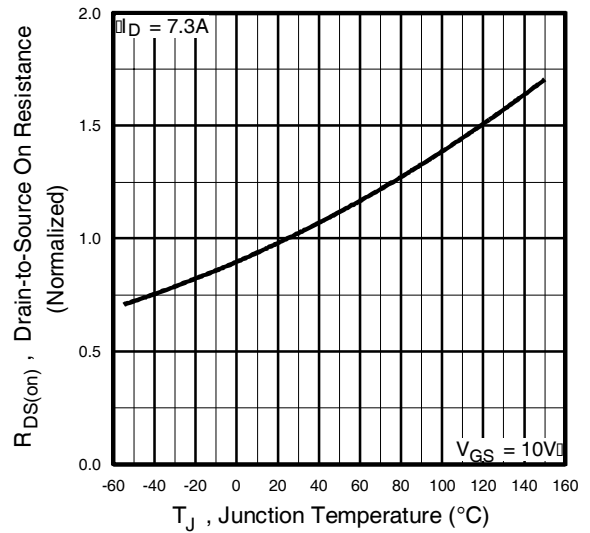
**Fig 1.** Typical Output Characteristics



**Fig 2.** Typical Output Characteristics

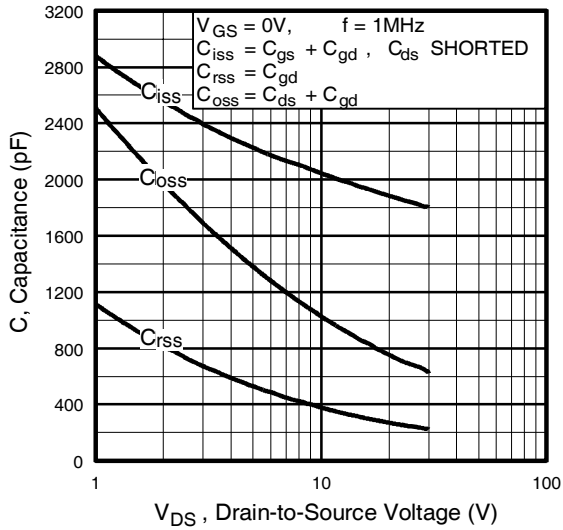


**Fig 3.** Typical Transfer Characteristics

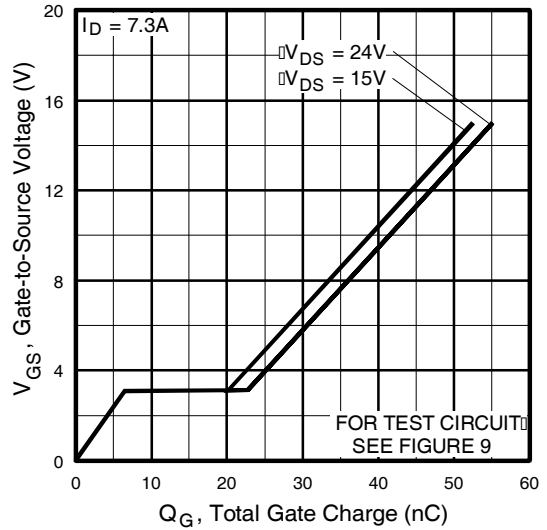


**Fig 4.** Normalized On-Resistance Vs. Temperature

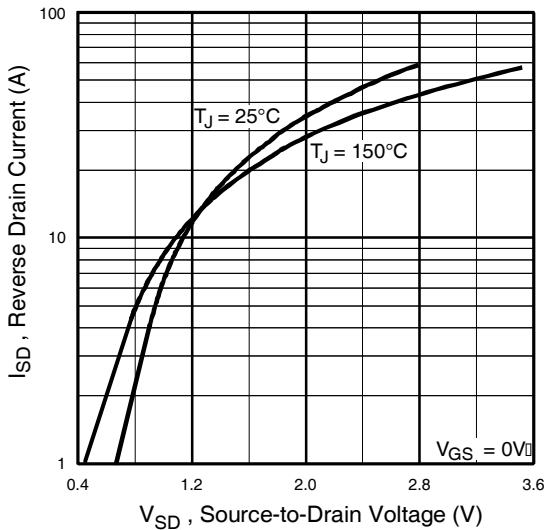
**Typical Characteristics**



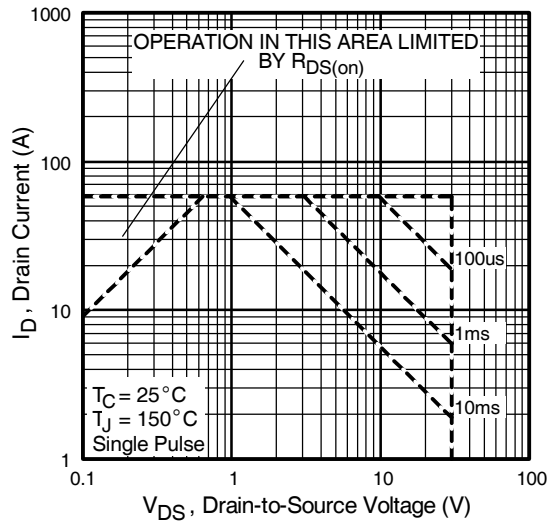
**Fig 5.** Typical Capacitance Vs. Drain-to-Source Voltage



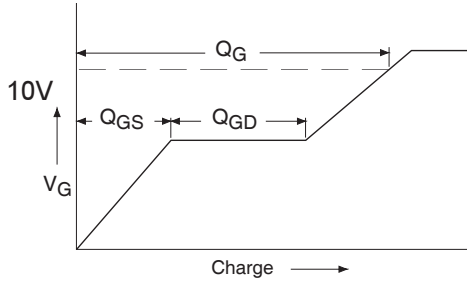
**Fig 6.** Typical Gate Charge Vs. Gate-to-Source Voltage



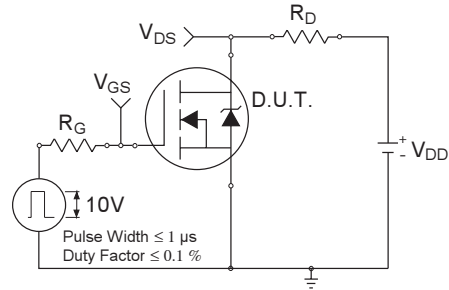
**Fig 7.** Typical Source-Drain Diode Forward Voltage



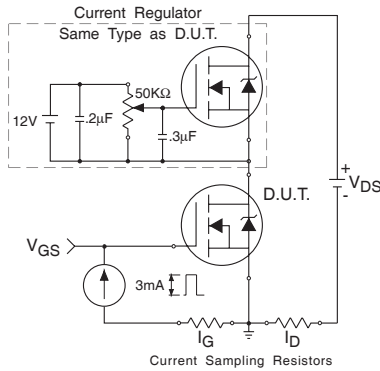
**Fig 8.** Maximum Safe Operating Area



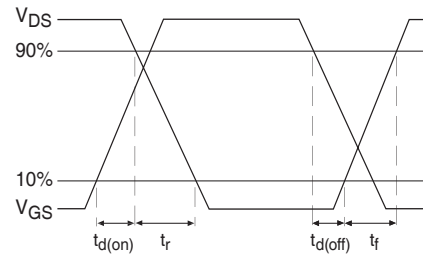
**Fig 9a. Basic Gate Charge Waveform**



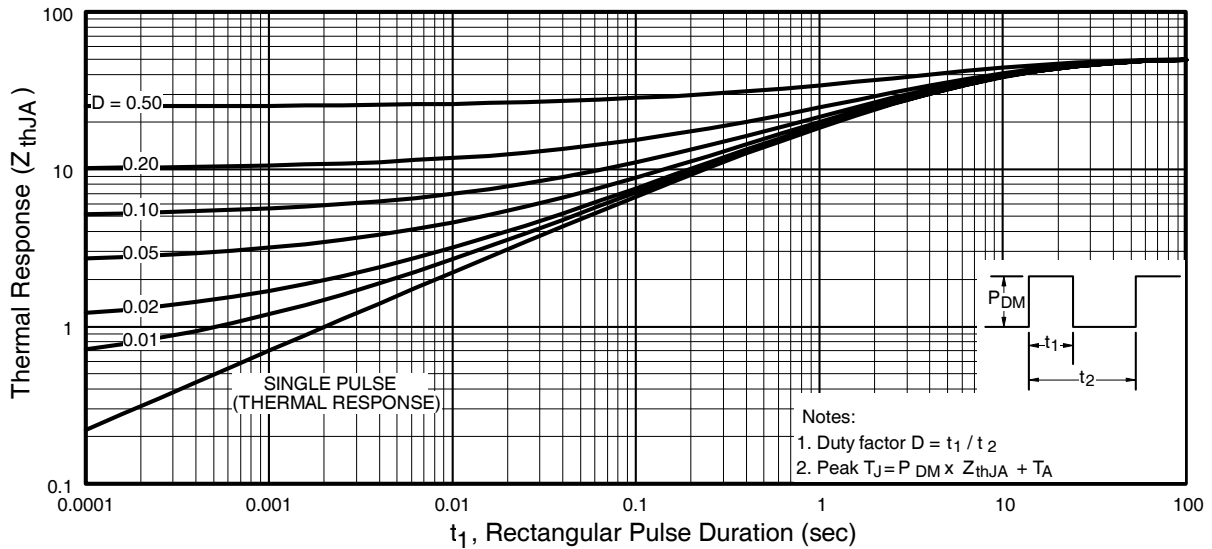
**Fig 10a. Switching Time Test Circuit**



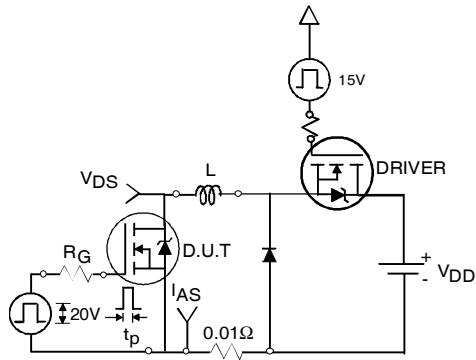
**Fig 9b. Gate Charge Test Circuit**



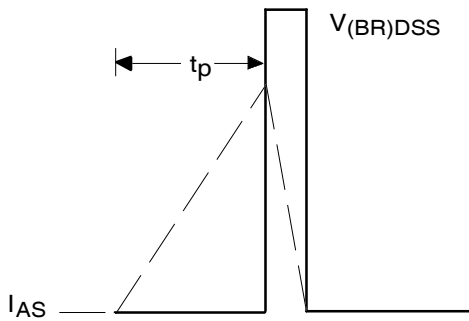
**Fig 10b. Switching Time Waveforms**



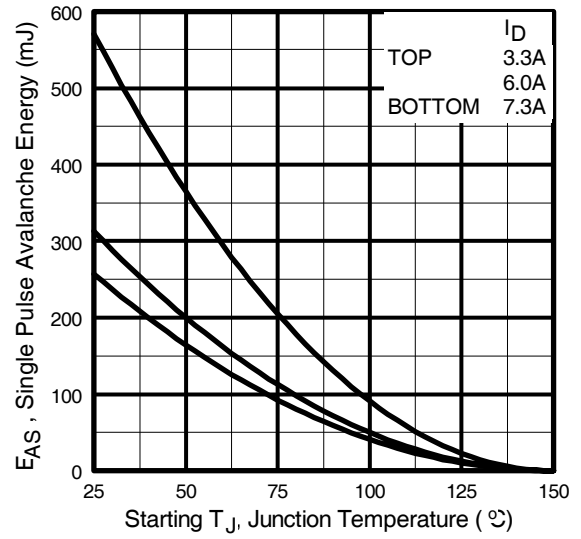
**Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Ambient**



**Fig 12a.** Unclamped Inductive Test Circuit

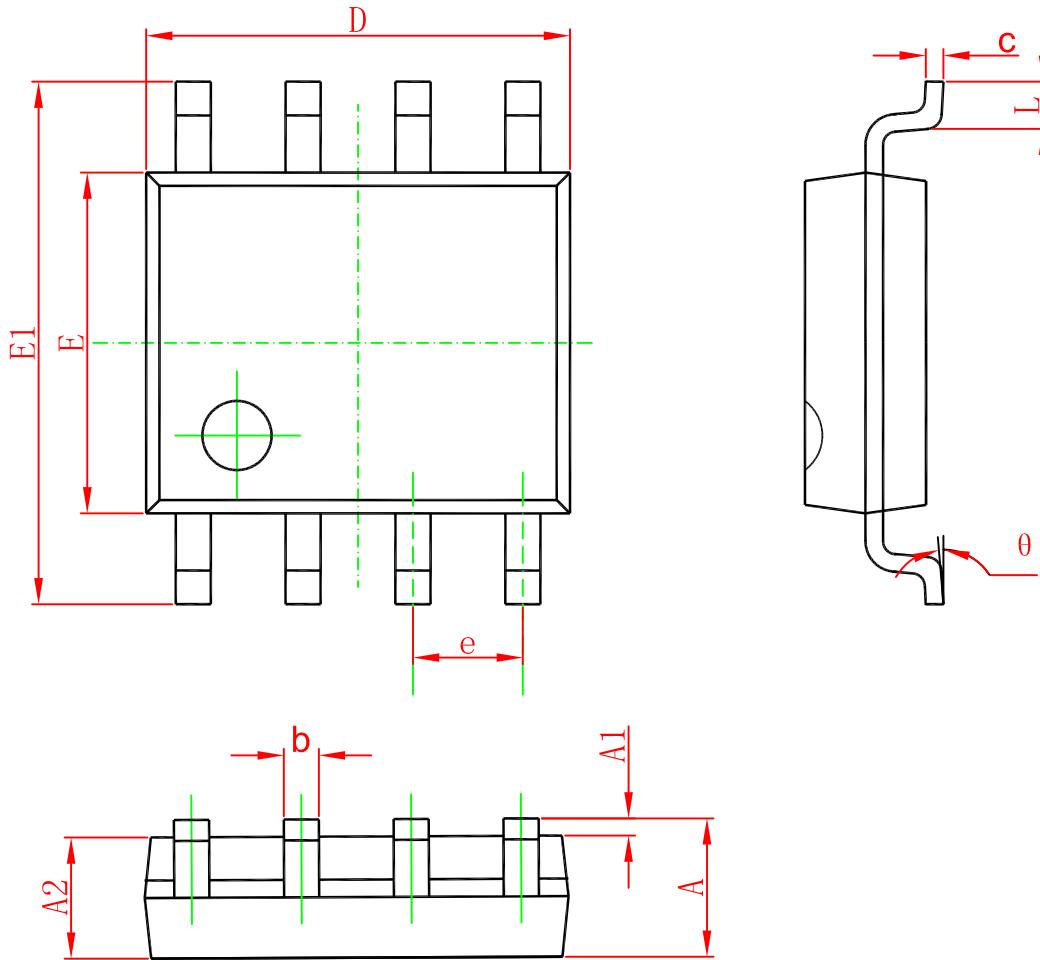


**Fig 12b.** Unclamped Inductive Waveforms



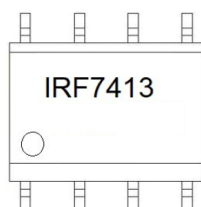
**Fig 12c.** Maximum Avalanche Energy Vs. Drain Current

**SOP-8**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270(BSC)		0.050(BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°

## Marking



## Ordering information

Order code	Package	Baseqty	Deliverymode
IRF7413	SOP-8	3000	Tape and reel